

Process:  
Subprocess:  
Product Family:

**PARTICLE SIZE REDUCTION**  
**WET-MILLING**  
**POLYTRON®**



## CHEMICAL

# Solder Powder: Reliable Joining of Electronic Components



### THE APPLICATION SCOPE / PURPOSE

Solder is a metal alloy used to join or connect electronic components together. In the electronic industry, solder powder is primarily used in the soldering process, which is the technique of melting the solder to form a permanent bond between two or more metal surfaces. The fine particle size of this powder allows for precise application and facilitates the formation of reliable solder joints. Kinematica offers solutions for the efficient particle size reduction of solder in a liquid medium overcoming the challenges this process implies.

Get full access to the Application Note by clicking this link:

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